L Number	Hits	Search Text	DB	Time stamp
1	. 1	("6403442").PN.	USPAT;	2003/04/08 15:50
			US-PGPUB	
2	1172	capacitor and HSG	USPAT;	2003/04/08 16:20
			US-PGPUB	
3	1092	(capacitor and HSG) and (opening or recess	USPAT;	2003/04/08 16:23
		or hole or trench or via or container)	US-PGPUB	
4	587	((capacitor and HSG) and (opening or	USPAT;	2003/04/08 16:24
		recess or hole or trench or via or	US-PGPUB	
		container)) and @ad<=19990902		

L Number	Hits		DB	Time stamp
1	465	HSG and ((opening or via or recess or	USPAT;	2003/04/09 14:31
		hole) with (filler or filling or	US-PGPUB	
		photoresist or resist or polymer))		
2	402		USPAT;	2003/04/09 14:16
		hole) with (filler or filling or	US-PGPUB	
		<pre>photoresist or resist or polymer))) and</pre>		
ĺ		capacitor		
3	216	1 1 2	USPAT;	2003/04/09 14:37
		hole) with (filler or filling or	US-PGPUB	j
		photoresist or resist or polymer))) and		
		capacitor) and @ad<=19990902		
4	27	(	EPO; JPO;	2003/04/09 14:30
		hole) with (filler or filling or	DERWENT;	
c	3266	photoresist or resist or polymer))	IBM_TDB USPAT:	2003/04/09 14:44
5	3200	438/396,398,253,255,666.ccls.	USPAT; US-PGPUB	2003/04/09 14:44
6	638	438/396,398,253,255,666.ccls. and HSG	USPAT;	2003/04/09 14:46
0	030	430/390,390,233,233,000.CC15. and nad	US-PGPUB	2003/04/09 14:46
7	396	(438/396,398,253,255,666.ccls. and HSG)	USPAT;	2003/04/09 14:46
'		and @ad<=19990902	US-PGPUB	2003/04/03 14.40
8	246		USPAT;	2003/04/09 14:37
		and @ad<=19990902) not (((HSG and	US-PGPUB	2000,01,00 21.01
	1	((opening or via or recess or hole) with	10000	
		(filler or filling or photoresist or		
		resist or polymer))) and capacitor) and		
		@ad<=19990902)		
9	1373	257/306-309.ccls.	USPAT;	2003/04/09 14:46
			US-PGPUB	
10	179	257/306-309.ccls. and HSG	USPAT;	2003/04/09 14:46
]			US-PGPUB	}
11	99	(257/306-309.ccls. and HSG) and	USPAT;	2003/04/09 14:47
	_	@ad<=19990902	US-PGPUB	
12	76	, , — - · , — · - · - · - · · · · · · · · · · · · ·	USPAT;	2003/04/09 14:47
		@ad<=19990902) not	US-PGPUB	
		(((438/396,398,253,255,666.ccls. and HSG)		1
}		and @ad<=19990902) not (((HSG and	1	
		((opening or via or recess or hole) with		
		(filler or filling or photoresist or		
		resist or polymer))) and capacitor) and		
L		@ad<=19990902))	L	

US-PAT-NO: 6207523

DOCUMENT-IDENTIFIER: US 6207523 B1

TITLE: Methods of forming capacitors DRAM

arrays, and

monolithic integrated circuits

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forming a solid mass of silicon material <u>filling an</u>
opening formed over a
node location defined by a doped region of the

semiconductor substrate, the mass comprising exposed doped silicon and exposed undoped silicon in contact

with one another, and including undoped silicon in physical contact with the node location;

forming a solid mass comprising two forms of silicon filling the opening and

in contact with one another, the two forms of silicon together forming a

capacitor storage node, the two forms of silicon including undoped silicon in

physical contact with the node location;

forming a solid mass of silicon material **filling the** opening, the silicon

material comprising doped silicon and undoped silicon in contact with one

another and defining a capacitor storage node, a portion of the undoped silicon

being in physical contact with the node location;

forming a doped silicon layer within the narrowed **opening** and in contact

with the undoped silicon layer, the undoped silicon layer and doped silicon

layer together **filling the opening** and defining a capacitor storage node;

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forming a second undoped silicon layer within the further narrowed opening and in contact with the doped silicon layer; the first undoped silicon layer, second undoped silicon layer and doped silicon layer together <u>filling the</u>
opening and defining a capacitor storage node;

filling the opening with silicon material, the silicon material comprising doped silicon and undoped silicon and defining a capacitor storage node, the undoped silicon being in contact with the node location;

29. The method of claim 26 wherein filling the opening with silicon material comprises forming a layer of doped polysilicon within a layer of undoped substantially amorphous silicon.

filling the narrowed opening with a doped silicon layer,
the undoped silicon
layer and doped silicon layer together defining a capacitor
storage node;

filling the opening with doped silicon;

filling the opening by forming the solid core of doped silicon within the opening, the doped silicon being separated from the node location by the undoped silicon.

	þ	H [	Document ID	Issue Date	Радея	0   + :F	Current OR
	)	<u>.</u> –			) ) ) 5	) 1 3 1 4	
1		⊠	US 20020031895 Al	20020314	24	METHOD TO REDUCE FLOATING GRAIN DEFECTS IN DUAL-SIDED CONTAINER CAPACITOR FABRICATION	438/396
2		☒	20020020	20020221	æ	MANU AVIN RODE	257/301
3		☒	US 20020017674 A1	20020214	12	CAPACITOR STRUCTURE	257/306
4		☒	US 6340613 B1	20020122	9	Structural integrity enhancement of dielectric films	438/240
5		Ø	US 6333241 B1	20011225	ω	Method for fabricating capacitor of semiconductor memory device	438/398
9			US 6326277 B1	20011204	14	i C	438/398
7		Ø	US 6323514 Bl	20011127	ω	Container structure for floating gate memory device and method for forming same	257/315
æ		· 🛛	US 6319789 B1	20011120	23	Method for improved processing and etchback of a container capacitor	438/396

	Current XRef	Retrieval Classif	Inventor	ß	υ	<u>D</u>	2	т	4	r.	Image Doc. Displayed	PT
П	438/255; 438/398	· ·	PING, ER-XUAN								US 20020031895	
			LEE, JOO-WON et al.	Ø							US 20020020866	
m			ROBERTS, MARTIN CEREDIG et al.	×							US 20020017674	
4	257/E21.267; 438/786; 438/787		DeBoer, Scott J.								US 6340613	
2	257/E21.013; 438/255		Kim, Hyeon-Soo	×							US 6333241	
9	57/E 38/2		DeBoer, Scott J.	Ø							US 6326277	
7	57/316; 57/317; 57/318; 57/323; 57/E29.12 38/211;		Kao, David Y.	⊠							US 6323514	
ω	257/E21.019; 430/316; 430/317; 438/244; 438/253; 438/638; 438/675; 438/675;		Carstensen, Robert K.	×							US 6319789	

	D	1 [1 ]	Document	ment ID	Issue Date	Pages	Title	Current OR
6		⊠	us 630	3953 B1	20011016	13	Integrated capacitor bottom electrode with etch stop layer	257/296
10		Ø	us 630	03430 B1	20011016	13	Method of manufacturing DRAM capacitor	438/253
11		×	us 628	1543 B1	20010828	12	Double layer electrode and barrier system on hemispherical grain silicon for use with high dielectric constant materials and methods for fabricating the same	257/309
12		×	us 628	1142 B1	20010828	16	Dielectric cure for reducing oxygen vacancies	438/771
13		☒	US 625	58691 B1	20010710	24	Cylindrical capacitor and method for fabricating same	438/398
14			US 6258	8664 B1	20010710	ω	Methods of forming silicon-comprising materials having roughened outer surfaces, and methods of forming capacitor constructions	438/255

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Image Doc. Displayed	US 6303953	US 6303430	US 6281543	US 6281142	US 6258691	US 6258664
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Inventor	Doan, Trung T. et al.	Jenq, J. S. Jason	Al-Shareef, Husam N. et al.	Basceri, Cem et al.	Kim, Yun-Gi	Reinberg, Alan R.
Retrieval Classif						
Current XRef	57/301 57/309 57/532 57/E21 57/E29	257/E21.019; 438/254; 438/255; 438/396; 438/397;	7/31 7/E2 8/24 8/25	257/103; 257/236; 257/240; 257/310; 257/E21.009; 257/E21.241; 322/10; 438/240; 438/402;	57/E2 57/E2	257/E21.013; 438/398; 438/491
	o _	10	11	12	13	14

5		D	111	Document ID	Issue Date	Pages	Title	Current OR
□ ⊠ US 6251742 B1 20010626         11         Method of manufacturing a cup-shape capacitor           □ № 0235571 B1 20010522         8         Uniform dielectric layer and method to form same           □ № 05211033 B1 20010403         10         Integrated capacitor bottom electrode for use with conformal dielectric           □ № 0187629 B1 20010213         9         Method of fabricating a DRAM capacitor           □ № 0159783 A 20001212         8         Structure and fabricating method of stacked capacitor method of stacked capacitor           □ № 0146961 A 20001114         18         Processing methods of forming a capacitor	15		Ø	6255159	20010703	13		438/253
S   Us 6235571 B1   20010522   8   Uniform dielectric layer and method to form same   Integrated capacitor bottom   Integrated capacitor bottom   conformal dielectric   Conformal d	9		Ø	6251742	20010626	11	of manufacturing ape capacitor	438/396
□         □         US 6211033 B1         20010403         10         electrode for use with conformal dielectric           □         □         □         US 6187629 B1         20010213         9         Method of fabricating a DRAM capacitor           □ <td>7</td> <td></td> <td>Ø</td> <td>6235571</td> <td>20010522</td> <td>8</td> <td>Uniform dielectric layer and method to form same</td> <td>438/240</td>	7		Ø	6235571	20010522	8	Uniform dielectric layer and method to form same	438/240
□       □	ω <sub>.</sub>		Ø	6211033	20010403	10	d capacitor for use wit dielectric	438/387
□       ⊠       US 6159793 A       20001212       8       Structure and fabricating method of stacked capacitor         □       ⊠       US 6159785 A       20001212       21       Semiconductor device and manufacturing method thereof         □       ⊠       US 6146961 A       200011114       18       Processing methods of forming a capacitor	6		⊠	6187629	20010213		fabricating a DRAM	438/255
□     □     □     □     Semiconductor device and manufacturing method thereof manufacturing method thereof       □     <	0		Ø	6159793	20001212	æ	and fabr stacked	438/255
□ ⊠ US 6146961 A 20001114 18 Processing methods of forming a capacitor	<del></del>		☒	6159785	20001212	21	device and method thereof	438/238
	22		Ø	6146961	20001114	18	rocessing methods of forming capacitor	438/396

	Current XRef	Retrieval Classif	Inventor	S	۵	Ā	2	e	4	5	Image Doc. Displayed	PŢ
	257/E21.012; 257/E21.648; 438/254; 438/255; 438/396; 438/397;		Thakur, Randhir P. S.							S D D	6255159	
	77		Lin, Yeh-Sen	Ø						sn 🗆	6251742	
	21.00 21.29 36;		Doan, Trung	⊠						sn [	6235571	
	21.00 21.01 21.64 14;		Sandhu, Gurtej S. et al.	⊠						Sη	6211033	
	257/E21.013; 438/253; 438/396; 438/398		Gau, Jing-Horng et al.	⊠						Sn 🗆	6187629	
	21.01 21.01 54		Lou, Chine-Gie	×						sn [	6159793	
:	21.01 53; 54		Tsuchimoto, Junichi et al.	×						sn [	6159785	
	257/E21.014; 257/E21.019; 257/E21.648; 257/E27.089; 438/253		Graettinger, Thomas M. et al.	×						sn C	6146961	

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23		⊠	us 6120	6847 A	20001003	ω	High selectivity etching process for oxides	216/57
24		$\boxtimes$	US 6124	6124607 A	20000926	11	Capacitive memory cell	257/309
25		☒	US 611077	0774 A	20000829	11	Method of forming a bit line over capacitor array of memory cells and an array of bit line over capacitor array of memory cells	438/253
26		$\boxtimes$	US 60491	9101 A	20000411	13	Processing methods of forming a capacitor, and capacitor construction	257/296
27		☒	US 596(	60294 A	19990928	10		438/398
28		☒	US 593(	5930641 A	19990727	11	forming an   circuit cor  tially rugge	438/398
29			US 5801	1413 A	19980901	13	Container-shaped bottom electrode for integrated circuit capacitor with partially rugged surface	257/301
30			US 54098	9855 A	19950425	10	Process for forming a semiconductor device having a capacitor	438/253

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Image Doc. Displayed	US 6126847	US 6124607	US 6110774	US 6049101	US 5960294	US 5930641	US 5801413	US 5409855
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Inventor	Thakur, Randhir et al.	Sandhu, Gurtej Singh et al.	Jost, Mark et al.	Graettinger, Thomas M. et al.	Zahurak, John K. et al.	Pan, Pai-Hung	Pan, Pai-Hung	Jun, Young-Kwon
Retrieval Classif								
Current XRef	257/E21.008; 257/E21.219; 257/E21.251; 257/E21.252	57/296; 57/308; 57/E21.01	57/E2 38/39	257/301; 257/308; 257/E21.019; 257/E21.648; 257/E27.089	7/E2 8/25	57/E2 57/E2 57/E2 38/25	4 4 4	57/E2 38/25 38/39 38/39 38/39
	23	24	25	26	27	28	29	30

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